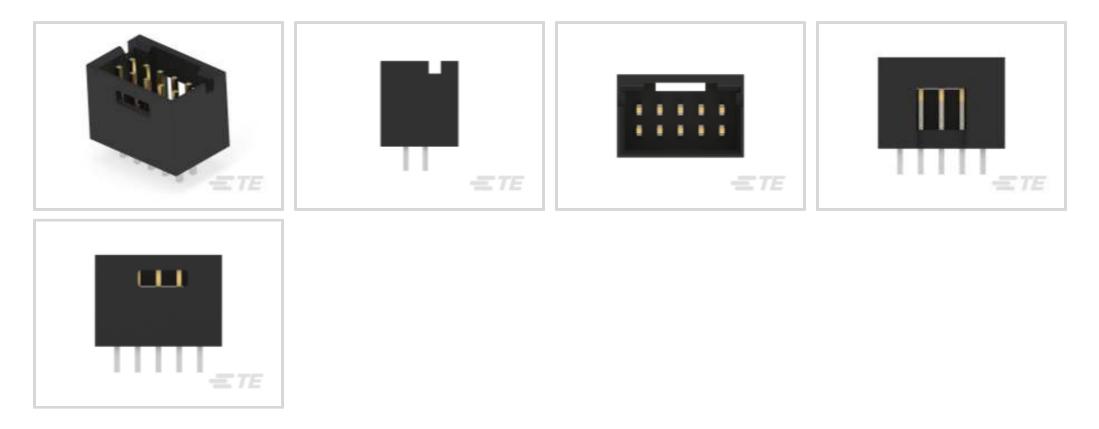
5-103168-3 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-103168-3 PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 10

Number of Rows: 2

Features

E T E connectivity

Product Type Features

PCB Connector Assembly Type	PCB Mount Header					
Connector System	Board-to-Board					
Header Type	Fully Shrouded					
Connector & Contact Terminates To	Printed Circuit Board					
Configuration Features						
Connector Contact Load Condition	Fully Loaded					
PCB Mount Orientation	Vertical					
Number of Positions	10					
Number of Rows	2					
Board-to-Board Configuration	Parallel					
Electrical Characteristics						
Insulation Resistance	5000 ΜΩ					
Dielectric Withstanding Voltage (Max)	750 Vrms					
Body Features						

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Connector Profile	Standard				
Primary Product Color	Black				
Contact Features					
Mating Square Post Dimension	.64 mm[.025 in]				
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]				
Contact Shape & Form	Square				
Contact Underplating Material	Nickel				
PCB Contact Termination Area Plating Material	Tin				
Contact Base Material	Phosphor Bronze				
Contact Mating Area Plating Material	Gold				
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]				
Contact Type	Pin				
Contact Current Rating (Max)	3 A				
Termination Features					
Square Termination Post & Tail Dimension	.64 mm[.025 in]				
Termination Post & Tail Length	3.18 mm[.125 in]				
Termination Method to Printed Circuit Board	Through Hole - Solder				

Mechanical Attachment

Mating Retention	With				
Mating Retention Type	Detent Window				
Mating Alignment	With				
Mating Alignment Type	Polarization				
PCB Mount Retention	Without				
PCB Mount Alignment	Without				
Connector Mounting Type	Board Mount				
Housing Features					
Centerline (Pitch)	2.54 mm[.1 in]				
Housing Material	Thermoplastic				
Dimensions					
Row-to-Row Spacing	2.54 mm[.1 in]				
PCB Thickness (Recommended)	1.4 mm[.055 in]				
Usage Conditions					

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Housing Temperature Rating	Standard			
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]			
Operation/Application				
Circuit Application	Signal			
Industry Standards				
Agency/Standard	CSA			
Approved Standards	CSA LR7189, UL E28476			
UL Flammability Rating	UL 94V-0			
Packaging Features				
Packaging Quantity	160			
Packaging Type	Tray			
Product Compliance For compliance documentation, visit the product page on TE.com>				
EU RoHS Directive 2011/65/EU	Compliant			
EU ELV Directive 2000/53/EC	Compliant			
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold			

EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
Solder Process Capability	Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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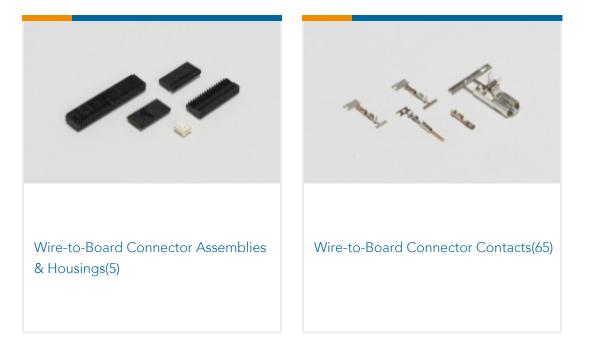




Also in the Series AMPMODU Headers



PCB Connector Mounting(1)		PCB Connector Shrouds(1)		PCB Headers & Receptacles(4875)		PCB Latches, Locks & Retainers(1)
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Customers Also Bought

PCB Mount Header, Vertical, Board-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





Documents

Product Drawings 10 MODII HDR DRST SHRD .100CL

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_5-103168-3_M.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-3_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-3_M.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Environmental Compliance MD_5-103168-3_10062015856_dmtec

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MD_5-103168-3_10062015856_dmtec

English

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